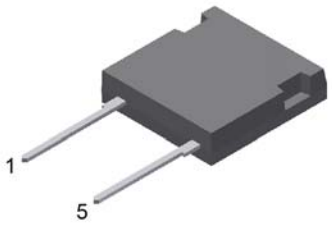
High Voltage Standard Rectifier

V_{RRM}	=	2200 V
I_{FAV}	=	30 A
V_F	=	1,22 V

Single Diode

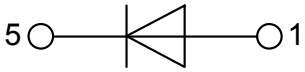
Part number

DNA30E2200FE



Backside: isolated

E72873



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very low forward voltage drop
- Improved thermal behaviour

Applications:

- Diode for main rectification
- For single and three phase bridge configurations

Package: i4-Pac

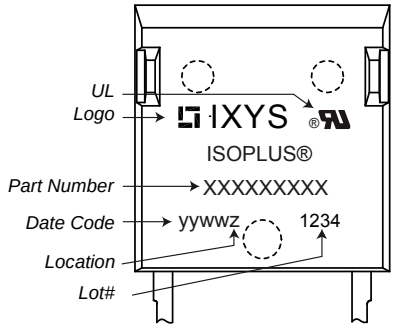
- Isolation Voltage: 3000 V~
- Industry convenient outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Soldering pins for PCB mounting
- Backside: DCB ceramic
- Reduced weight
- Advanced power cycling

Rectifier

Symbol	Definition	Conditions		Ratings min.	typ.	max.	Unit
V_{RSM}	*max. non-repetitive reverse blocking voltage*		T_{VJ} = 25°C			2300	V
V_{RRM}	*max. repetitive reverse blocking voltage*		T_{VJ} = 25°C			2200	V
I_R	*reverse current*	V_R = 2200 V	T_{VJ} = 25°C			40	µA
		V_R = 2200 V	T_{VJ} = 150°C			1,5	mA
V_F	*forward voltage drop*	I_F = 30 A	T_{VJ} = 25°C			1,25	V
		I_F = 60 A				1,50	V
		I_F = 30 A	T_{VJ} = 150°C			1,22	V
		I_F = 60 A				1,59	V
I_{FAV}	*average forward current*	T_C = 110°C	T_{VJ} = 175°C			30	A
		rectangular d = 0.5					
V_{F0}	*threshold voltage* } *for power loss calculation only*		T_{VJ} = 175°C			0,83	V
r_F	*slope resistance* }					12,8	mΩ
R_{thJC}	*thermal resistance junction to case*					1,35	K/W
R_{thCH}	*thermal resistance case to heatsink*				0,2		K/W
P_{tot}	*total power dissipation*		T_C = 25°C			110	W
I_{FSM}	*max. forward surge current*	t = 10 ms; (50 Hz), sine	T_{VJ} = 45°C			370	A
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			400	A
		t = 10 ms; (50 Hz), sine	T_{VJ} = 150°C			315	A
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			340	A
I^2t	*value for fusing*	t = 10 ms; (50 Hz), sine	T_{VJ} = 45°C			685	A²s
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			665	A²s
		t = 10 ms; (50 Hz), sine	T_{VJ} = 150°C			495	A²s
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			480	A²s
C_J	*junction capacitance*	V_R = 700 V; f = 1 MHz	T_{VJ} = 25°C		7		pF

Package i4-Pac				Ratings			
Symbol	**Definition**	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
I_{RMS}	*RMS current*	per terminal				70	A
T_{VJ}	*virtual junction temperature*			-55		175	°C
T_{op}	*operation temperature*			-55		150	°C
T_{stg}	*storage temperature*			-55		150	°C
Weight					5,5		g
F_C	*mounting force with clip*			20		120	N
$d_{Spp/App}$	*creepage distance on surface | striking distance through air*		*terminal to terminal*	13,8			mm
$d_{Spb/Apb}$			*terminal to backside*	5,1			mm
V_{ISOL}	*isolation voltage*	t = 1 second	50/60 Hz, RMS; I_{ISOL} ≤ 1 mA	3000			V
		t = 1 minute		2500			V

Product Marking



Part description

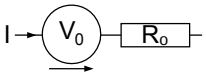
D = Diode
N = High Voltage Standard Rectifier
A = (>= 2000V)
30 = Current Rating [A]
E = Single Diode
2200 = Reverse Voltage [V]
FE = i4-Pac (2HV)

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DNA30E2200FE	DNA30E2200FE	Tube	25	508861

Similar Part	Package	Voltage class
DNA30E2200PA	TO-220AC	2200
DNA30E2200PZ	TO-263AB (D2Pak) (2HV)	2200
DNA30EM2200PZ	TO-263AB (D2Pak) (2HV)	2200
DNA30E2200IY	TO-262 (2HV) (I2PAK)	2200

Equivalent Circuits for Simulation

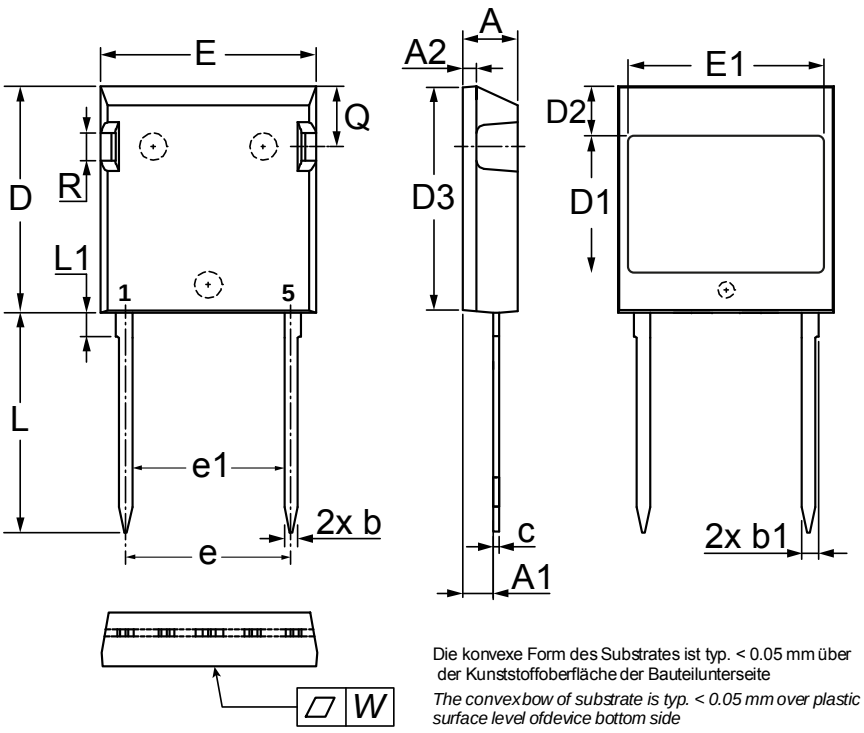
** on die level* T_{VJ} = 175°C



Rectifier

$V_{0\ max}$	*threshold voltage*	0,83	V
$R_{0\ max}$	*slope resistance **	10,2	mΩ

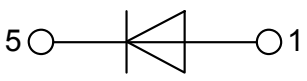
Outlines i4-Pac



Die konvexe Form des Substrates ist typ. < 0.05 mm über der Kunststoffoberfläche der Bauteilunterseite

The convexbow of substrate is typ. < 0.05 mm over plastic surface level ofdevice bottom side

Dim.	Millimeter		Inches	
	min	max	min	max
A	4.83	5.21	0.190	0.205
A1	2.59	3.00	0.102	0.118
A2	1.17	2.16	0.046	0.085
b	1.14	1.40	0.045	0.055
b1	1.47	1.73	0.058	0.068
c	0.51	0.74	0.020	0.029
D	20.80	21.34	0.819	0.840
D1	11.70	12.30	0.460	0.484
D2	5.50	6.10	0.216	0.240
D3	20.30	20.70	0.799	0.815
E	19.56	20.29	0.770	0.799
E1	17.50	18.10	0.689	0.712
e	15.24	BSC	0.600	BSC
e1	14.10	BSC	0.555	BSC
L	19.81	21.34	0.780	0.840
L1	2.11	2.59	0.083	0.102
Q	5.33	6.20	0.210	0.244
R	2.54	4.57	0.100	0.180
W	-	0.10	-	0.004



Rectifier

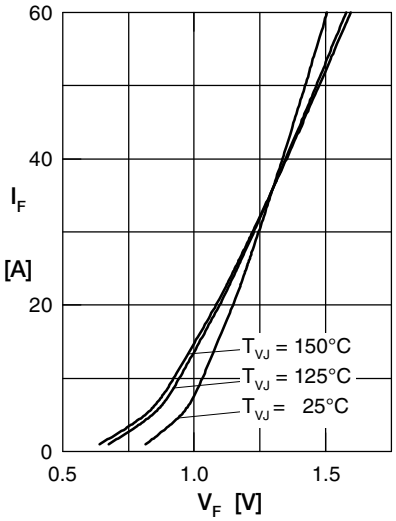


Fig. 1 Forward current versus voltage drop per diode

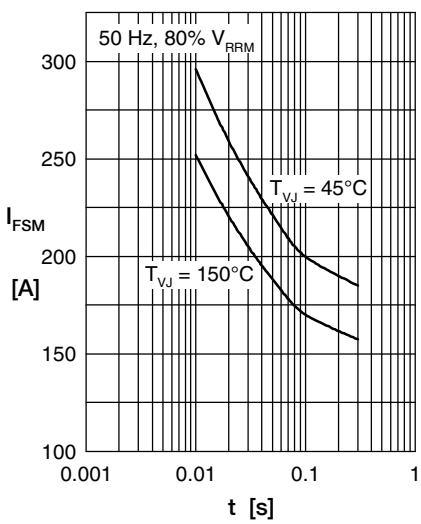


Fig. 2 Surge overload current

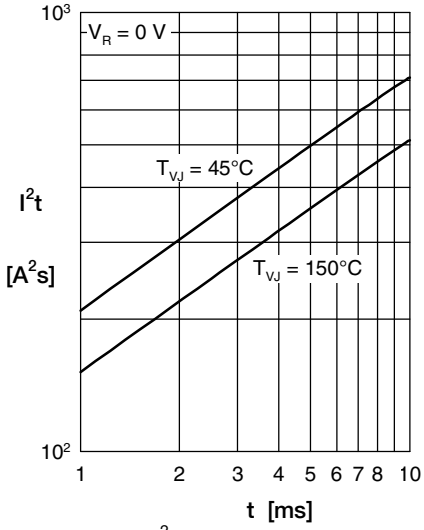


Fig. 3 I^2t versus time per diode

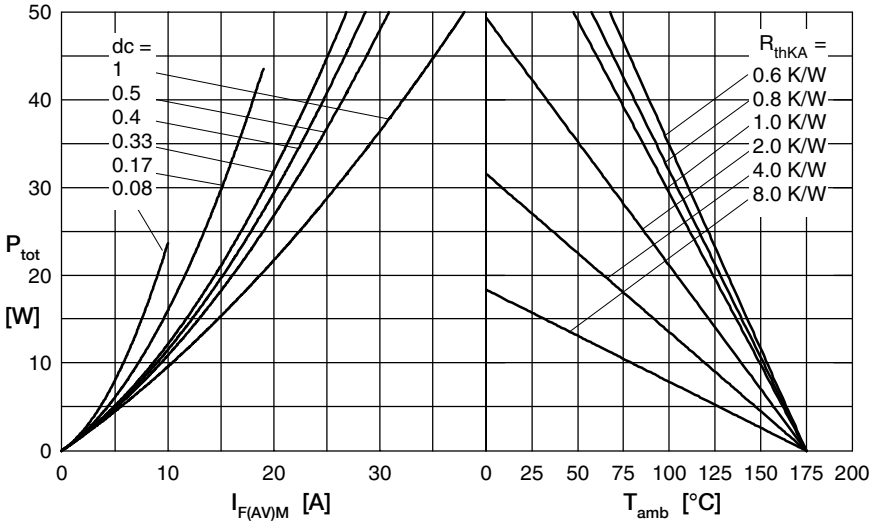


Fig. 4 Power dissipation versus direct output current & ambient temperature

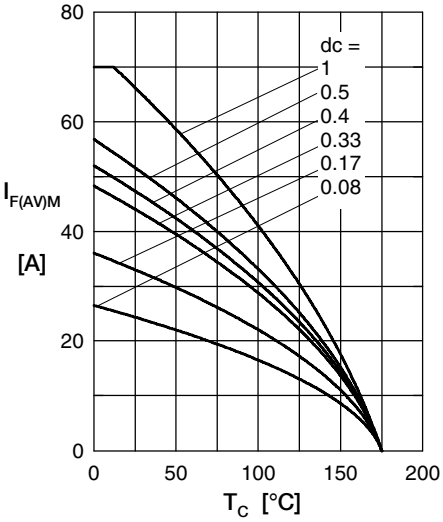


Fig. 5 Max. forward current versus case temperature

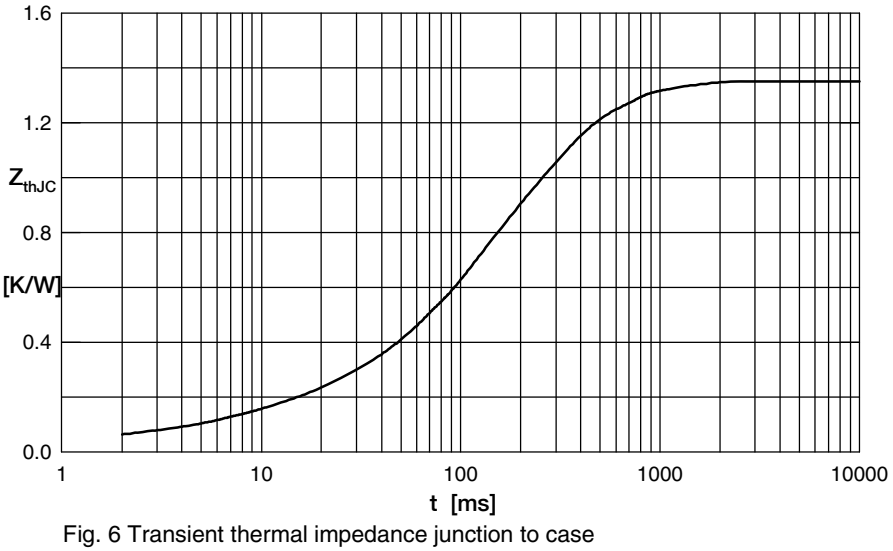


Fig. 6 Transient thermal impedance junction to case

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.03	0.0003
2	0.072	0.0065
3	0.122	0.083
4	0.736	0.152
5	0.39	0.4